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 TI **Tin-sodium solder** alloy, **solder** wire, and  
**soldering** method using it  
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PRAI	JP 1998-160596		19980609		

AB The **solder** alloy comprises 0.0001-10 wt.% Na and bal. **Sn**, optionally with 0.001-50 wt.% of Pb, In, **Bi**, Ge, **Sb**, **Cu**, Zn, and/or Ag in total. The **solder** wire comprises a Na core wire covered with **Sn** or its alloy, where ratio of Na in the **solder** wire is 0.0001-10 wt.%. **Soldering** method by using the **solder** alloy or wire in a reducing atm., inert gas atm., or vacuum is also claimed. No or a little flux is required for the **soldering** with the Pb-free **solder** alloy or wire, and the resulting **solder** joints have high strength.